(Product Change Notification)

Tuesday, January 14, 2014

PCN# 010214

To Whom It May Concern:

Please be advised NorComp has made a design change to item number listed below. Our records show that you have purchased some of these products in the last 5 years. Updated (rev.3) & previous (rev.1) drawings are attached on page 2 and 3 of this letter.

Part Number: 810-002-LP1R001

Change Description: New Insulator mold and new Stamping Die

We appreciate your understanding as we strive to offer you the most current information regarding our product.

Please confirm receipt & acceptance of product change notification (by returning signed copy by fax or email) and contact us if you need any additional assistance.

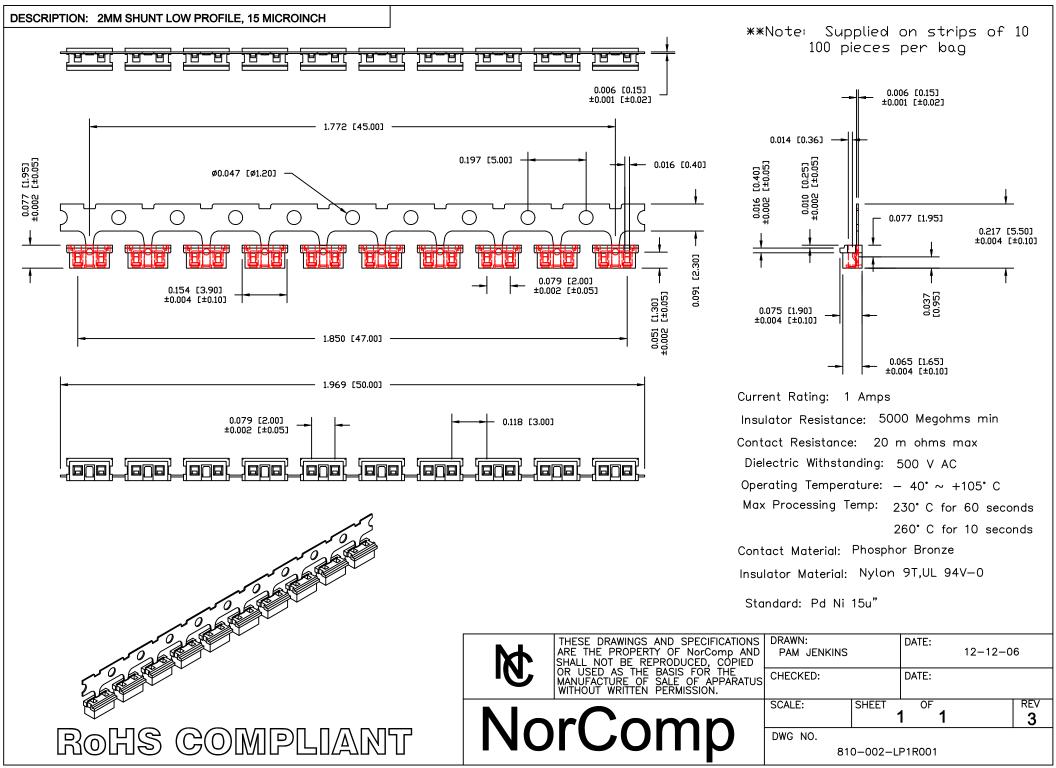
Regards, Pam Jenkins Engineering/Q.A. Manager Fax: 704-424-5648

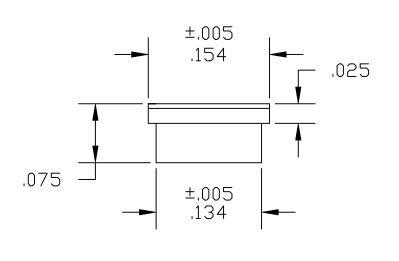
Approved By: ______

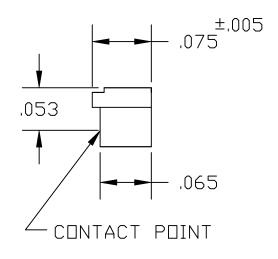
Company: _____

Title: _____

Date:







MATERIAL: HOUSING: HIGH TEMP. (PA-6T) 260° PROCESS TEMP.

CONTACT: BERYLLIUM COPPER

PLATING: 15 MICRO-INCHES PALLADIUM/NICKEL WITH GOLD FLASH OVERALL

ELECTRICALS: CURRENT RATING: 1.0 AMPERE MAX.

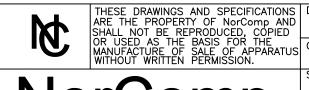
CONTACT RESISTANCE: 20 MILLIOHM MAX.

RIC WITHSTANDING: 250 VAC @SEA LEVEL

INSULATION RESISTANCE: 10,000 MOHMS MIN.

OPERATING TEMP: -55°C TO 105°C

ROHS COMPLIANT



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PRAWN: PAM JENKINS	DATE: 12-12-06
CHECKED:	DATE:

REV 1

SCALE: SHEET

DWG NO.

810-002-LP1R001